

Electronic Patent Application Fee Transmittal

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|---|--|-----------------|---------------|-----------------------------|
| Application Number: | 10607782 | | | |
| Filing Date: | 27-Jun-2003 | | | |
| Title of Invention: | Liquid solder thermal interface material contained within a cold-formed barrier and methods of making same | | | |
| First Named Inventor/Applicant Name: | Sabina J. Houle | | | |
| Filer: | Joseph P. Mehrle/Anne Richards | | | |
| Attorney Docket Number: | 884.860US1 | | | |
| Filed as Large Entity | | | | |
| Utility Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-----------------------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Request for continued examination | 1801 | 1 | 790 | 790 |
| Total in USD (\$) | | | | 790 |